ABSTRACT

Technique relating to establishment of a method for preventing epoxy-bleed-out that does not adversely affect die-bonding strength or assembly properties and that does not impair a discoloration prevention effect or sealing treatment effect, including an agent for preventing epoxy-bleed-out in a die-bonding step in a semiconductor manufacturing process characterized in that it contains at least one organic compound selected from carboxylic acids or thiols having three or more carbon atoms in the straight chain, carboxylic acids or thiols having benzene rings, carboxylic acids containing mercapto groups or hydroxy groups, unsaturated polyalcohols, nitrogen-containing heterocyclic compounds containing sulfurs in the molecules, and derivatives thereof.